# Accepted Manuscript

ISSN 0925-8388

Journal of
ALLOYS
AND COMPOUNDS

An Interdisciplinary Journal
of Materials Science and
Solid-State Chemistry and Physics

Interfacial reactions at the joints of $CoSb_3$-based thermoelectric devices

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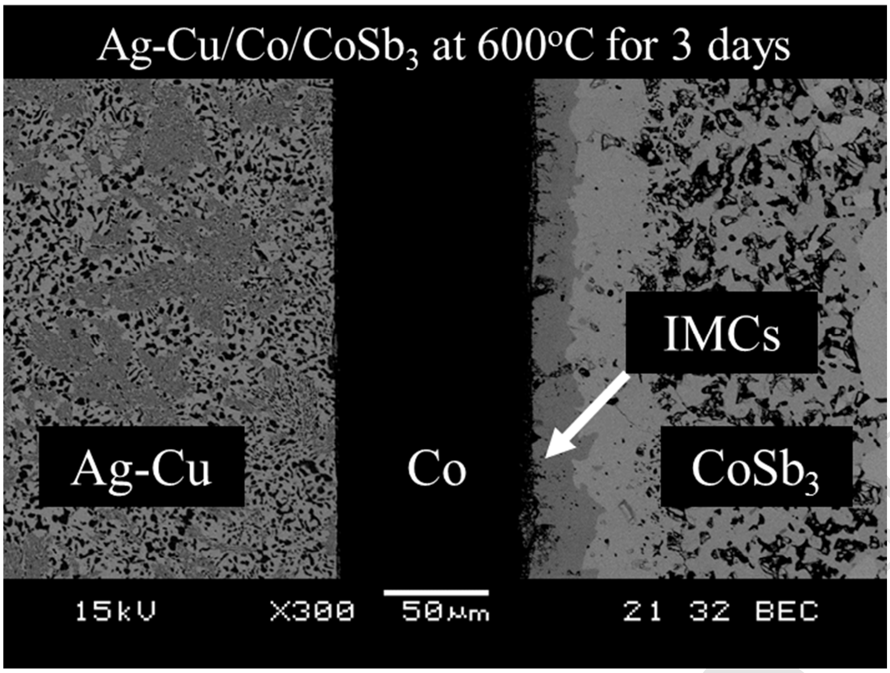
PII: S0925-8388(16)34315-8
DOI: 10.1016/j.jallcom.2016.12.386
Reference: JALCOM 40309

To appear in: *Journal of Alloys and Compounds*

Received Date: 8 October 2016
Revised Date: 23 November 2016
Accepted Date: 28 December 2016

Please cite this article as: S.-w. Chen, A.H. Chu, D.S.-H. Wong, Interfacial reactions at the joints of $CoSb_3$-based thermoelectric devices, *Journal of Alloys and Compounds* (2017), doi: 10.1016/j.jallcom.2016.12.386.


Ag-Cu/Co/CoSb$_3$ at 600$^o$C for 3 days
IMCs
Ag-Cu
Co
CoSb$_3$
15kV
X300
50µm
21 32 BEC